

MATERIAL DECLARATION SHEET



Reliable Electronic Solutions

Material	MF-RHT
Product Line	Multifuse
Revision Date	November 15, 2005
Revision	A
RoHS Compliant	Yes



No	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg. Sn alloy, Cu Copper)	Material/ substance weight in grams ($\pm 0.1\%$)	CAS No. / Int. Identifier	Material / Substance Weight %	Sum (%)
1	Epoxy Coating Powder	Bis-Phenol Epoxy Resin	0.01748	25068-38-6	5.42%	14.27%
		Brominated Epoxy Resin	0.00460	26265-08-7	1.43%	
		Silica Crystalline	0.01840	14808-60-7	5.71%	
		Antimony Trioxide	0.00138	1309-64-4	0.43%	
		Iron Oxide Fume	0.00253	1309-37-1	0.78%	
		Titanium Dioxide	0.00161	13463-67-7	0.50%	
2	Solder	Sn	0.03416	7440-31-5	10.60%	10.67%
		Cu	0.00024	7440-50-8	0.07%	
3	Wire	Cu	0.17044	7440-50-8	52.88%	53.15%
		Sn	0.00069	7440-31-5	0.21%	
		Fe	0.00017	7439-89-6	0.05%	
4	Foil	Copper	0.04902	7440-50-8	15.21%	16.01%
		Nickel	0.00258	7440-02-0	0.80%	
5	Polymer	Flourine Type Homopolymer	0.01177		3.65%	3.65%
		Proprietary Additives	0.00001		0.00%	
6	Carbon Black	C	0.00722	1333-86-4	2.24%	2.24%

Total weight (grams)	0.32230	Total	100.00%	100.00%
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